

U.S. 09/754,264  
Atty. Docket No.: OKI.202*Pre  
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1/29/03*

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Tetsuo Usami, et al.

Group Art Unit: 2814

Serial No.: 09/754,264

Examiner: S.H. Rao

Filed: January 5, 2001

For: Deposition Method For Wiring Thin Film

Honorable Assistant Commissioner of Patents  
Washington, D.C. 20231

Date: January 23, 2003

**Preliminary Amendment**

Sir:

The present Preliminary Amendment is being submitted for consideration upon initial examination of an Request for Continued Examination (RCE) application filed concurrently herewith.

**FAX RECEIVED**

JAN 23 2003

TECHNOLOGY CENTER 2800

**In the claims:**

1. Please cancel claims 1-9 without prejudice or disclaimer of the subject matter thereof.
2. Please add the following claims:

10. (Newly Added) A method of depositing a wiring thin film over a semiconductor substrate, the method comprising:

*B1  
cont.*